



1

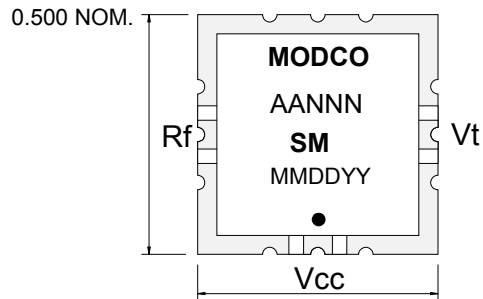
2

3

4

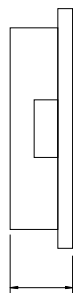
**TOP VIEW**

GND



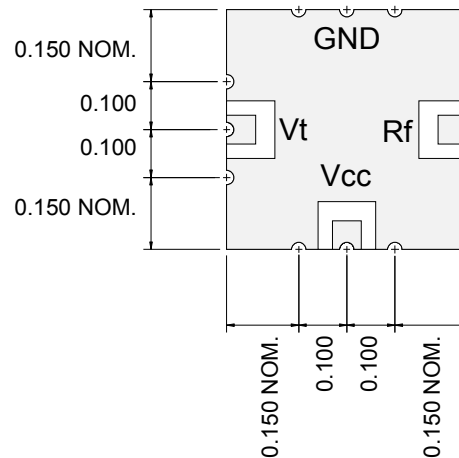
0.500 NOM.

**SIDE VIEW**



0.130 MAX.

**BOTTOM VIEW**



C

C

B

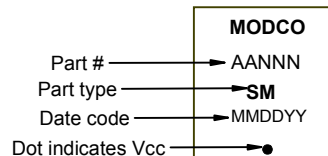
B

**Notes:**

1. The case is ground.
2. Soldermask/pad layout may vary depending on model, consult factory.
3. Unless otherwise specified all dimensions are in inches.
4. Unless otherwise specified finish is 150-200 micro inches nickel over copper clad PCB, 5-15 micro inches malleable, 99.99% pure gold, over nickel.

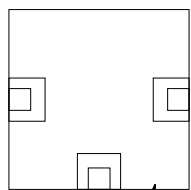
**Part labeling**

Part number: AA=Alpha pre-fix, product family or custom part designator.  
 NNN=Numeric 3 to 4 digit specific part number  
 Part type: 2 to 4 alpha part type designator  
 Date code: MM=month, DD=day, YY=year  
 Label material is high temp. Kapton® film, opaque white, with black marking.



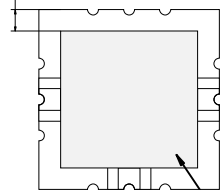
**Solder mask/finish detail. See note 2.**

fig. 1



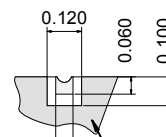
Finish is electrolysis gold over nickel barrier.

0.075 TYP fig. 2



Shaded area is solder mask.

PAD DETAIL TYP



Shaded area is conductor.

A

A

E	Add RoHS info, revise detail text
D	Delete Opt 3, change finish
C	Add I/O designators.
B	Updated address from 808 to 806.
A	Released on new format.

**Revision History**

DATE: 08/15/07	<b>MODCO, INC.</b> 806 PACKER WAY SPARKS NV 89431 TEL: (775) 331-2441 FAX: (775) 331-6266
BY: D. Johnson	
CHECKED:	
REV: E	
DRAWING #: SM_SPEC_E.mkd	TITLE: SM PACKAGE OUTLINE

1

2

3

4